

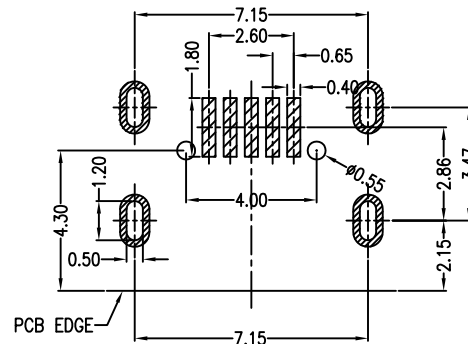
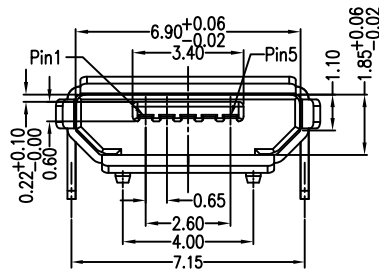
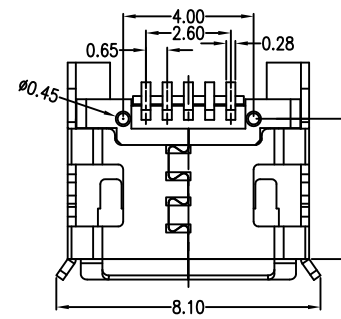
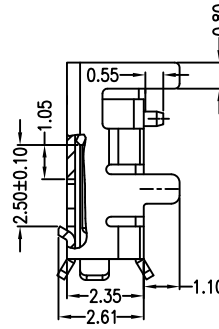
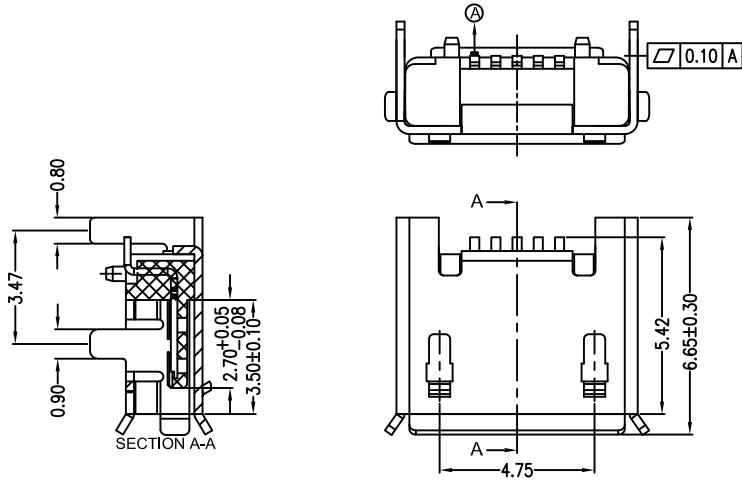
RoHS

MAPX

MODIFICATION

DRW

DATE



RECOMMENDED PCB LAYOUT

PCB图仅供参考

Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.20mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:

- 2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.
- 2.7 Temp rature range: -30°C~80°C

产品图

PRODUCT CHART DWG

公差一览表

TOLERANCE UNLESS OTHERWISE

X.	±0.25	X.	±5°
.X	±0.20	.X	±2°
.XX	±0.15	.XX	±1°
.XXX	±0.10	.XXX	±0.5°



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单位

MM

制图

Z-Y-B

制图料号

B920-ECA52A2021S10110

比例

1:1

审核

产品名称

MICRO/SP-F 四脚插板7.2有边有柱加卡点
0.4mm端子贴板

日期

2016-09-09

核准

角法

版本

VER

A0

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